



SOT2008-1

thermal enhanced low profile fine-pitch land grid array
package, 13 terminals, 0.5 mm pitch, 2.2 mm x 2.2 mm x 0.68
mm body

2 July 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HFLGA12
Package style descriptive code	HLLGA (thermal enhanced low profile land grid array)
Mounting method type	S (surface mount)
Issue date	05-02-2020
Manufacturer package code	98ASA01395D

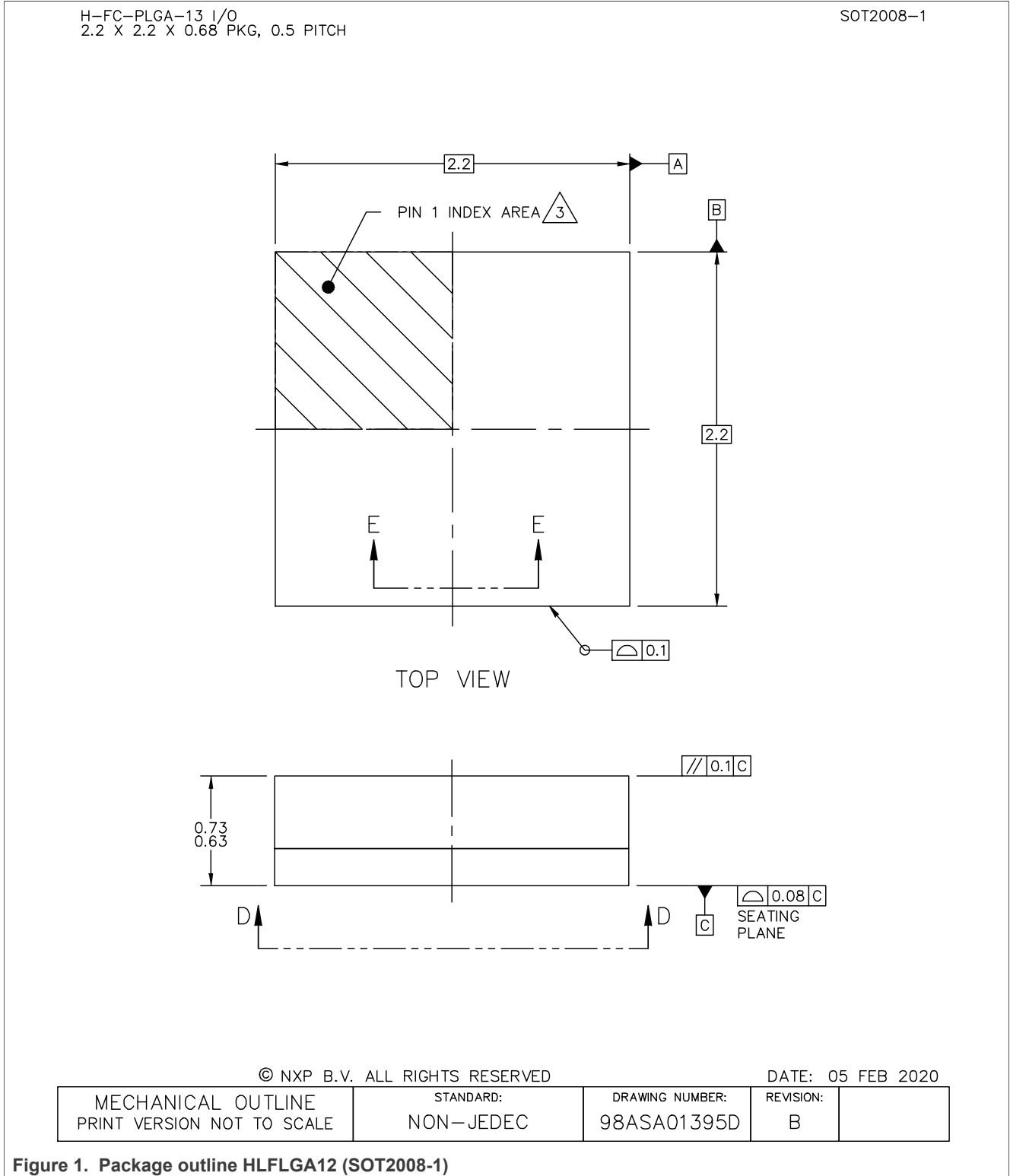
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.1	2.2	2.3	mm
package width	2.1	2.2	2.3	mm
package height	0.63	0.68	0.73	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	13	-	

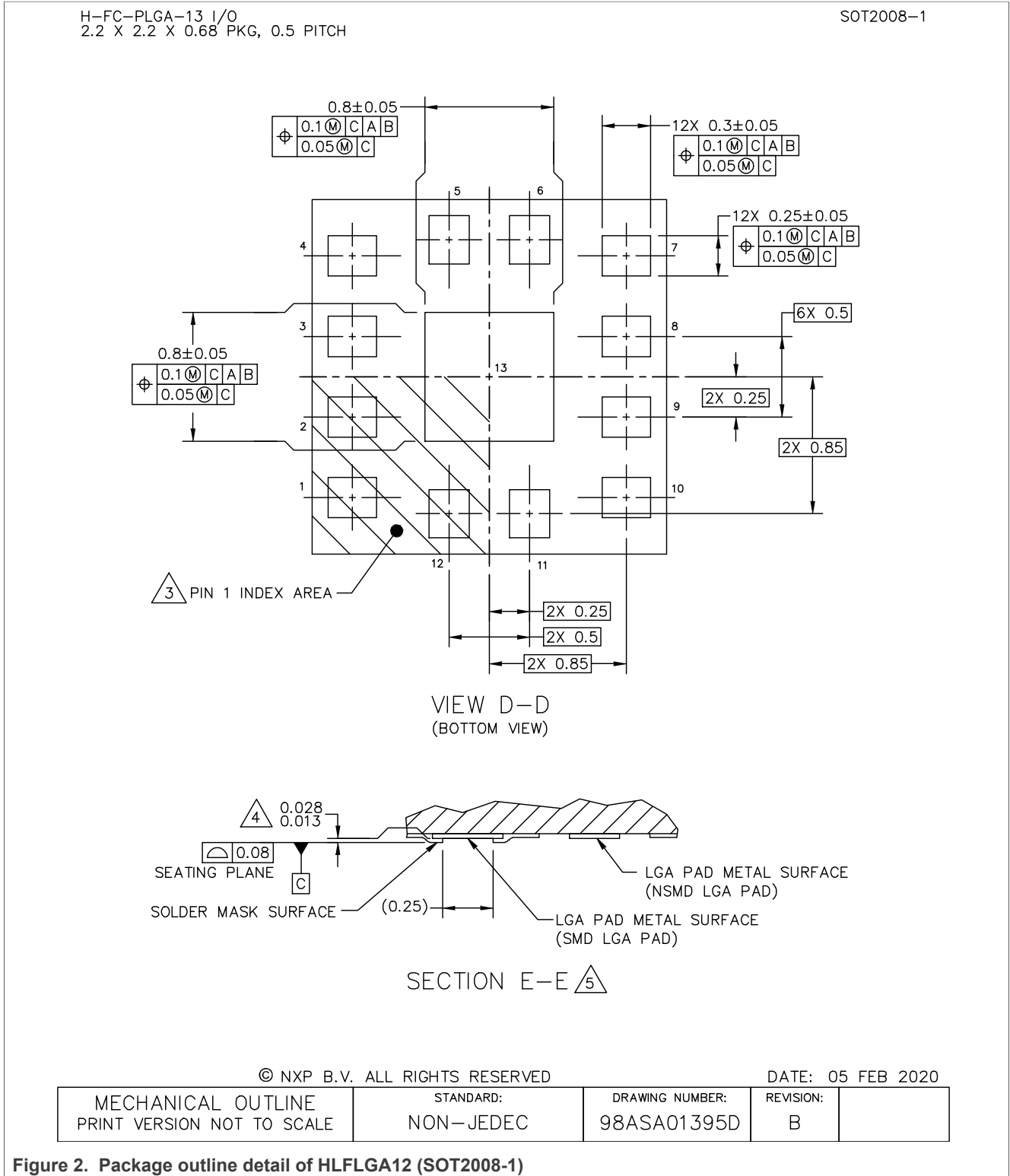


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2 Package outline

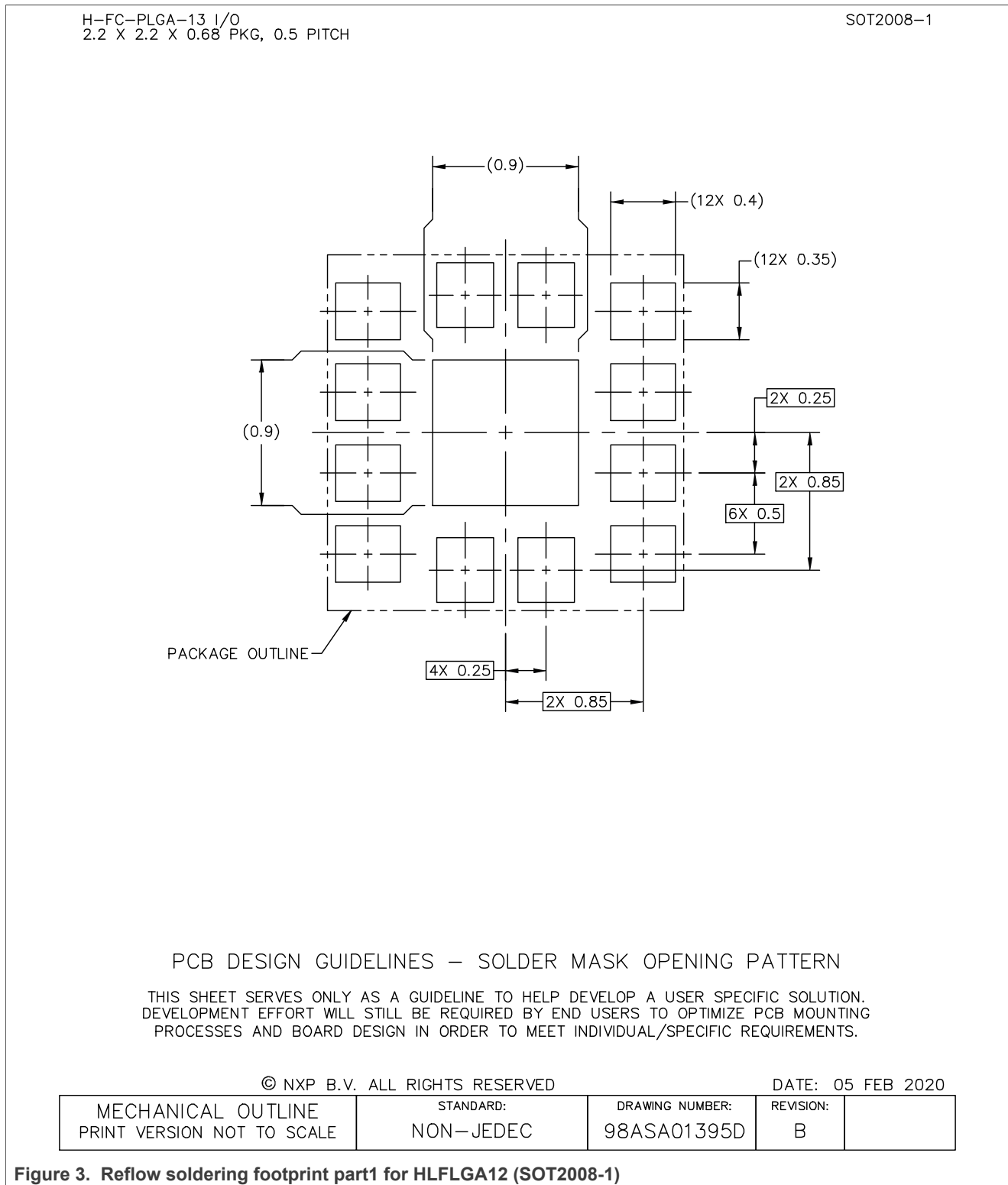


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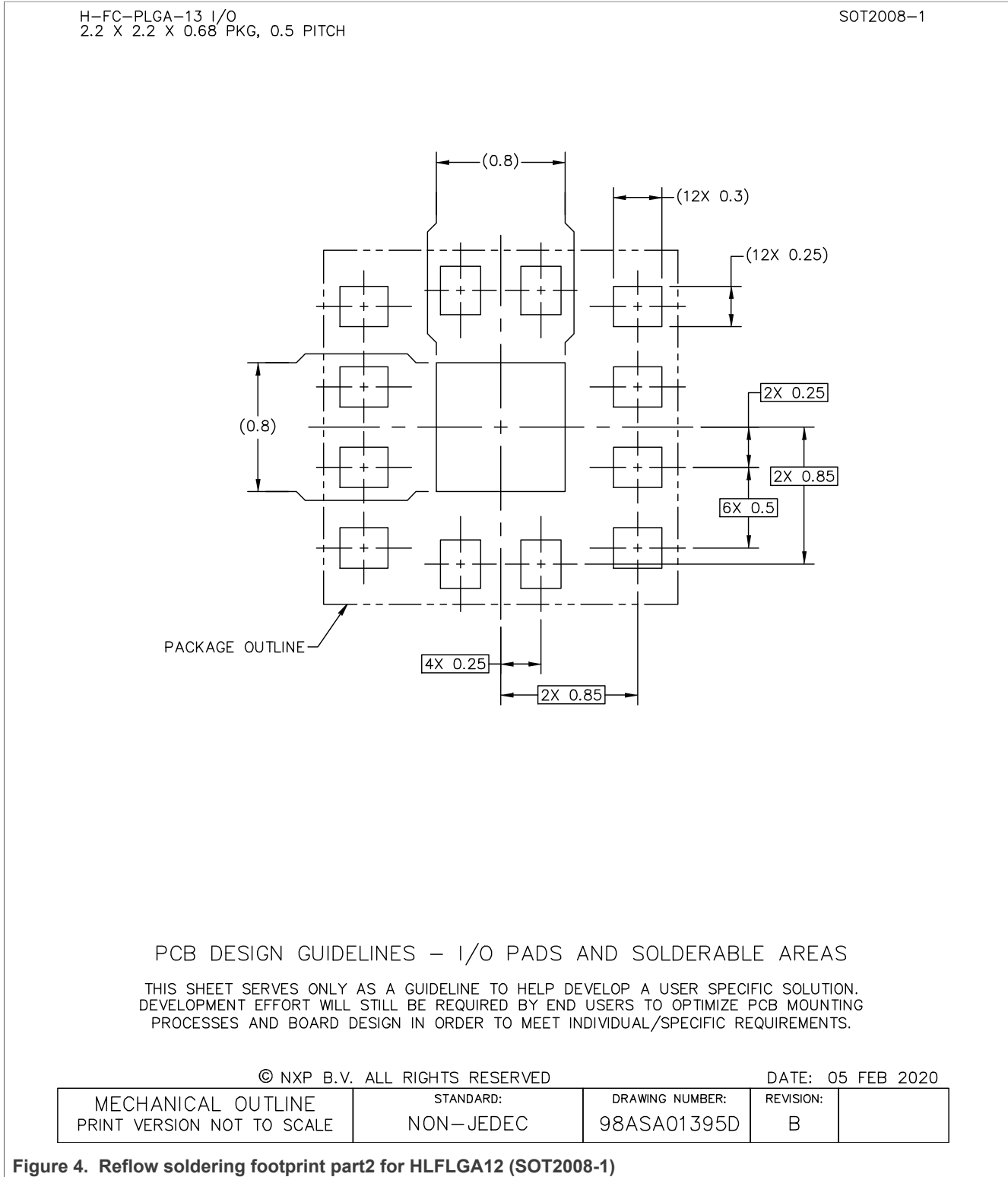


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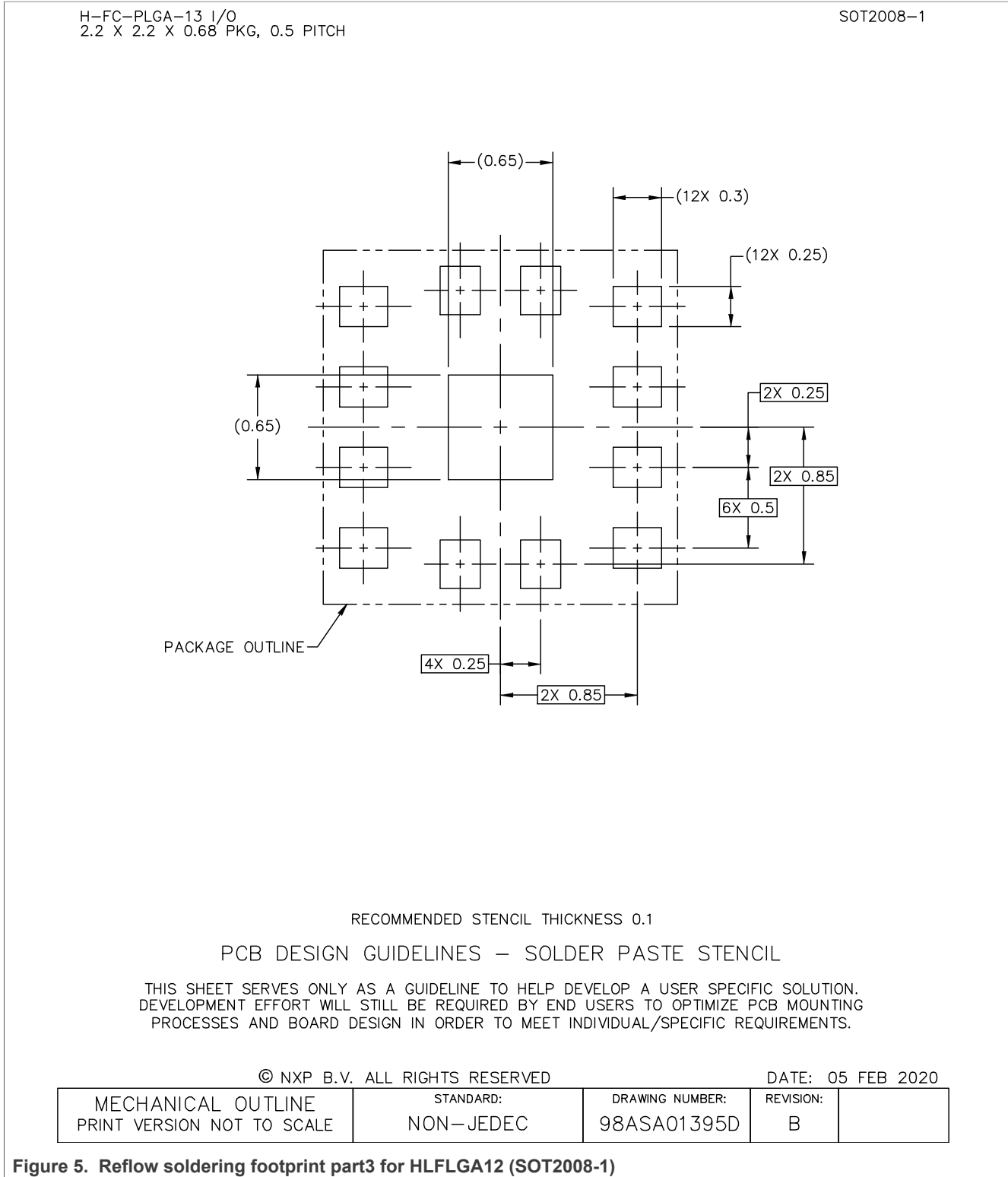
3 Soldering



thermal enhanced low profile fine-pitch land grid array package, 13 terminals, 0.5 mm pitch, 2.2 mm x 2.2 mm x 0.68 mm body



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H-FC-PLGA-13 I/O
2.2 X 2.2 X 0.68 PKG, 0.5 PITCH

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DIMENSION APPLIES TO ALL LEADS AND FLAG.
5. THE BOTTOM VIEW SHOWS THE SOLDERABLE AREA OF THE PADS. THE CENTER PAD (PIN 13) IS SOLDER MASK DEFINED. SOME PERIPHERAL PADS ARE SOLDER MASK DEFINED (SMD) AND OTHERS ARE NON-SOLDER MASK DEFINED (NSMD).

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DATE: 05 FEB 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01395D	REVISION: B	
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Figure 6. Package outline note HLFLGA12 (SOT2008-1)

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4 Legal information

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